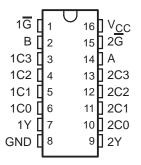
SN54HC153, SN74HC153 DUAL 4-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS112D - DECEMBER 1982 - REVISED OCTOBER 2003

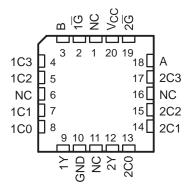
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 9 ns
- ±6-mA Output Drive at 5 V

SN54HC153...J OR W PACKAGE SN74HC153...D, N, NS, OR PW PACKAGE (TOP VIEW)



- Low Input Current of 1 μA Max
- Permit Multiplexing from n Lines to One Line
- Perform Parallel-to-Serial Conversion
- Strobe (Enable) Line Provided for Cascading (N Lines to n Lines)

SN54HC153 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

Each of these data selectors/multiplexers contains inverters and drivers to supply full binary decoding data selection to the AND-OR gates. Separate strobe (\overline{G}) inputs are provided for each of the two 4-line sections.

ORDERING INFORMATION

TA	PACKA	GE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC153N	SN74HC153N
		Tube of 40	SN74HC153D	
–40°C to 85°C	SOIC - D	Reel of 2500	SN74HC153DR	HC153
		Reel of 250	SN74HC153DT	
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HC153NSR	HC153
		Tube of 90	SN74HC153PW	
	TSSOP - PW	Reel of 2000	SN74HC153PWR	HC153
		Reel of 250	SN74HC153PWT	
	CDIP – J	Tube of 25	SNJ54HC153J	SNJ54HC153J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC153W	SNJ54HC153W
	LCCC - FK	Tube of 55	SNJ54HC153FK	SNJ54HC153FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54HC153, SN74HC153 DUAL 4-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

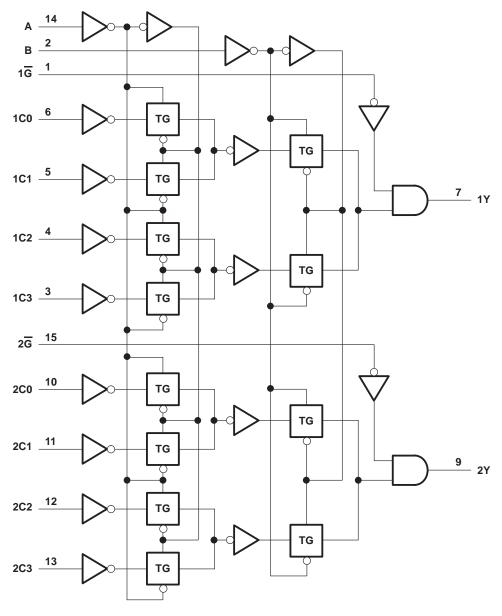
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FUNCTION TABLE

-			INPUTS				
SELI	ЕСТ†		DA	G	OUTPUT Y		
В	Α	C0	C1	C2	C3	G	ī
Х	Χ	Χ	Χ	X	Χ	Н	L
L	L	L	X	X	X	L	L
L	L	Н	Χ	X	Χ	L	Н
L	Н	Χ	L	X	Χ	L	L
L	Н	Χ	Н	X	Χ	L	Н
Н	L	Χ	Χ	L	Χ	L	L
Н	L	Χ	Χ	Н	Χ	L	Н
Н	Н	Х	Χ	Χ	L	L	L
Н	Н	Х	Χ	Χ	Н	L	Н

[†] Select inputs A and B are common to both sections.

logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, PW, and W packages.

SN54HC153, SN74HC153 DUAL 4-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5	$V \ to \ 7 \ V$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)		±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c) (see Note 1)		±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	- 		$\pm 35~\text{mA}$
Continuous current through V _{CC} or GND			±70 mA
Package thermal impedance, θ _{JA} (see Note 2):	: D package		73°C/W
	N package		67°C/W
	NS package		64°C/W
	PW package	1	108°C/W
Storage temperature range, T _{stg}		–65°C t	io 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SI	N54HC15	i3	SN	174HC15	i3	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
VIH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
		V _{CC} = 2 V			0.5			0.5	
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V
		V _{CC} = 6 V			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V		-	500		-	500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SN54HC153, SN74HC153 DUAL 4-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	7507.00	MIDITIONS	.,	Т	A = 25°C	;	SN54H	IC153	SN74H	C153	UNIT
PARAMETER	TEST CC	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
VoL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10	·	10		10	pF

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	,,	T	ղ = 25°C	;	SN54F	IC153	SN74H	C153																						
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT																					
			2 V		90	150		225		190																						
	A or B	Υ	4.5 V		21	30		45		38																						
			6 V		17	26		38		32																						
	Data (Any C)		2 V		73	126		189		158																						
^t pd		Y	4.5 V		17	28		42		35	ns																					
·			6 V		14	23		35		29																						
	ĪG		2 V		38	95		150		125																						
		Υ	4.5 V		11	19	28 2		24																							
			6 V		9	16		24		20																						
			2 V		20	60		90	·	75																						
tţ		Υ	Y	Y	Y	Υ	Y	Y	Y	Y	Υ	Υ	Υ	Y	Y	Y	Y	Y	Y	Y	Y	Y	Y	4.5 V		8	12		18	·	15	ns
			6 V		6	10		15		13																						

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switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

	FROM	то	,,	T	λ = 25°C	;	SN54H	C153	SN74H	C153			
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT		
			2 V		105	235		355		295			
	A or B	Y	Y	Υ	4.5 V		27	47		71		59	
			6 V		21	41		60		51			
	Data (Any C)		2 V		93	220		335		274			
t _{pd}		Y	4.5 V		23	44		67		55	ns		
,			6 V		19	38		57		48			
			2 V		60	185		280		230			
	G	Y	4.5 V		17	37		56		46			
			6 V		14	32		48		40			
			2 V		45	210		315		265			
t _t		Y	4.5 V		17	42		63		53	ns		
			6 V		13	36		53		45			

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per multiplexer	No load	40	pF

PARAMETER MEASUREMENT INFORMATION **VCC** From Output Test Input 50% 50% **Under Test Point** CL tPLH → (see Note A) In-Phase ۷он 90% 50% Output **LOAD CIRCUIT** VOL **⋖** tPHL - VCC Input 90% Out-of-Phase 50% Output ۷oı **VOLTAGE WAVEFORM VOLTAGE WAVEFORMS** PROPAGATION DELAY AND OUTPUT TRANSITION TIMES **INPUT RISE AND FALL TIMES**

- NOTES: A. C_L includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
 - C. The outputs are measured one at a time with one input transition per measurement.
 - D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8409301VEA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8409301VE A SNV54HC153J	Samples
5962-8409301VFA	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8409301VF A SNV54HC153W	Samples
84093012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84093012A SNJ54HC 153FK	Samples
8409301EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8409301EA SNJ54HC153J	Samples
SN54HC153J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC153J	Samples
SN74HC153D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153	Samples
SN74HC153DE4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153	Samples
SN74HC153DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153	Samples
SN74HC153DRE4	ACTIVE	SOIC	D	16	2500	TBD	Call TI	Call TI	-40 to 85		Samples
SN74HC153N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC153N	Samples
SN74HC153NE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC153N	Samples
SN74HC153NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153	Samples
SN74HC153PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153	Samples
SN74HC153PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153	Samples
SN74HC153PWT	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC153	Samples
SNJ54HC153FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84093012A SNJ54HC 153FK	Samples

PACKAGE OPTION ADDENDUM

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54HC153J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8409301EA SNJ54HC153J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC153, SN54HC153-SP, SN74HC153:



PACKAGE OPTION ADDENDUM

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● Catalog : SN74HC153, SN54HC153

• Military : SN54HC153

• Space : SN54HC153-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All differsions are nominal	all difficults are nominal													
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant		
SN74HC153DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1		
SN74HC153NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1		
SN74HC153PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1		
SN74HC153PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1		

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC153DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC153NSR	SO	NS	16	2000	853.0	449.0	35.0
SN74HC153PWR	TSSOP	PW	16	2000	853.0	449.0	35.0
SN74HC153PWT	TSSOP	PW	16	250	853.0	449.0	35.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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